

1/7  
FIG.1

0 ND FILTER

		PHYSICAL THICKNESS (nm)
6 ~	SiO <sub>2</sub>	78
5 ~	Ti, TiO <sub>2</sub> , Ti <sub>2</sub> O <sub>3</sub> , TiO, TiN	25
4 ~	SiO <sub>2</sub>	51
3 ~	Ti, TiO <sub>2</sub> , Ti <sub>2</sub> O <sub>3</sub> , TiO, TiN	28
2 ~	SiO <sub>2</sub>	59
1 ~	SUBSTRATE ; PET	0.1 (mm)

2/7

FIG. 2

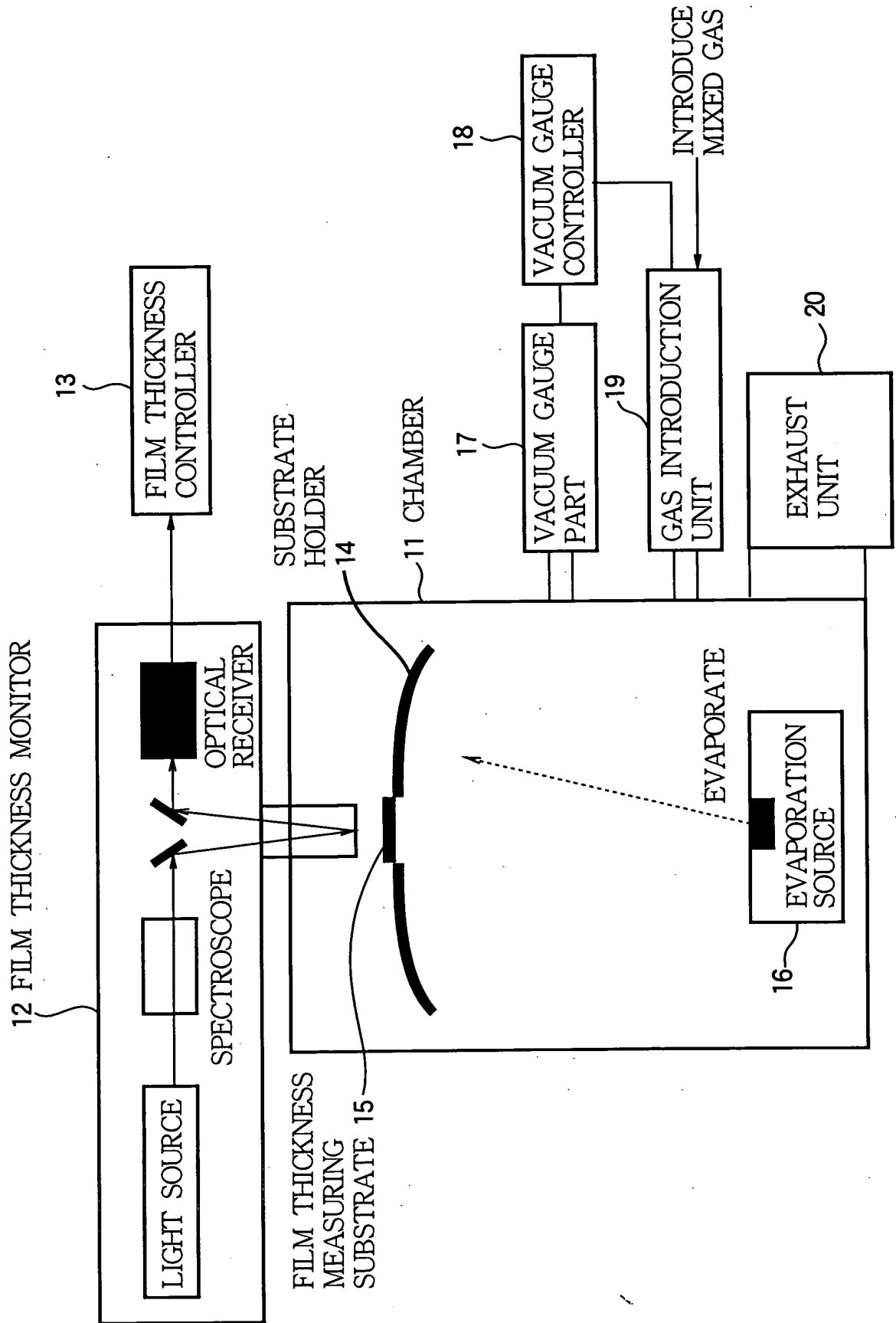


FIG.3

SUBSTRATE TEMPERATURE		100°C	
ULTIMATE VACUUM DEGREE		$1 \times 10^{-3}$ Pa	
FILM FORMATION CONDITIONS	Ti	DEPOSITION RATE	0.5~1nm/sec
		DEPOSITION VACUUM DEGREE	$3 \sim 4 \times 10^{-3}$ Pa
		INTRODUCED GAS	Air (N2 : O2=4 : 1)
		DEPOSITION RATE	0.5~1nm/sec
	SiO2	INTRODUCED GAS	—

4/7

FIG.4

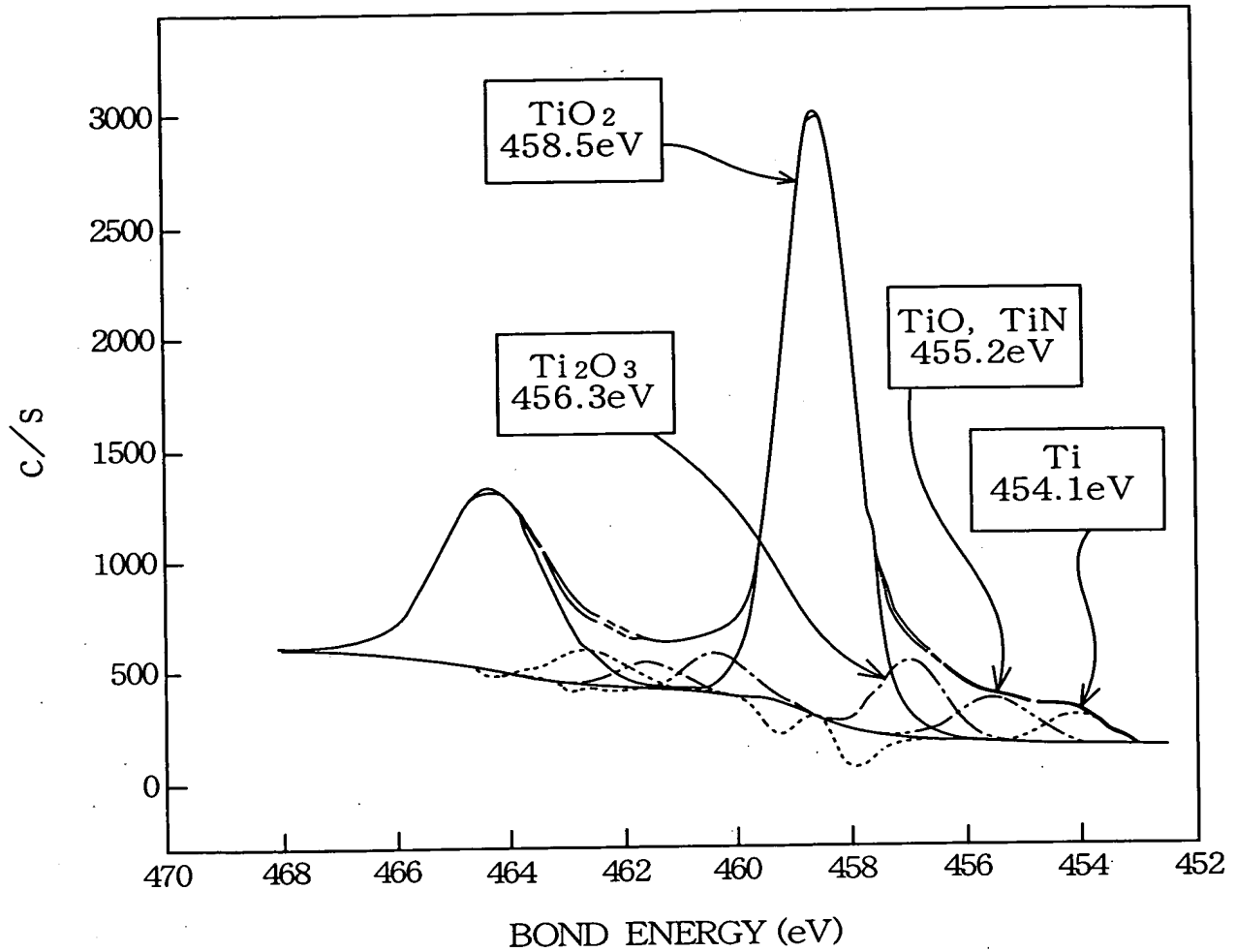


FIG.5

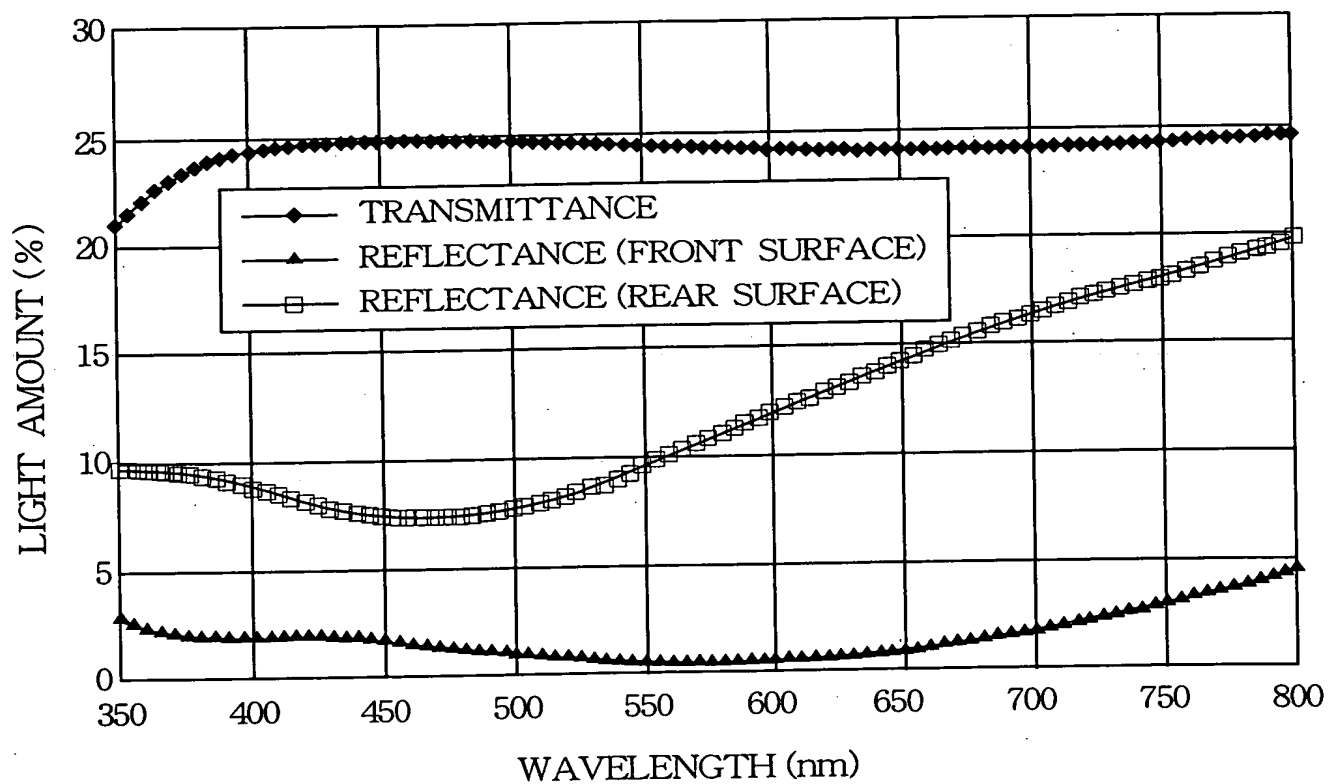
	Ti (METAL)	TiO or TiN	Ti <sub>2</sub> O <sub>3</sub>	TiO <sub>2</sub>
ENERGY (eV)	454.1	455.2	456.7	458.5
PROPORTION (%)	5%	5%	10%	80%

5/7

FIG.6

	C	N	O	Ti
PROPORTION(%)	(16.5%)	2.8%	53.8%	27.5%

FIG.7



6/7

FIG.8

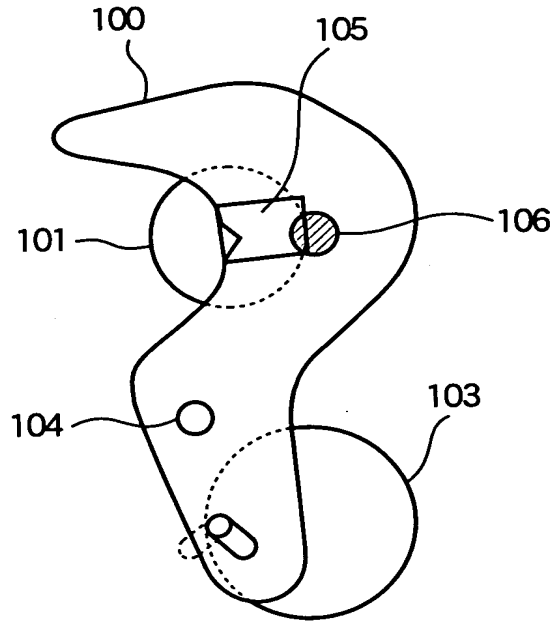
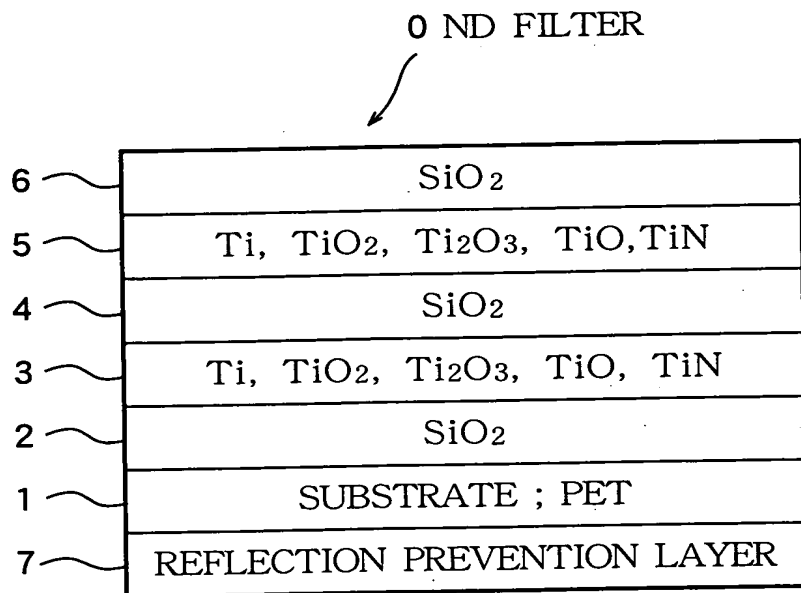


FIG.9



7/7

FIG. 10

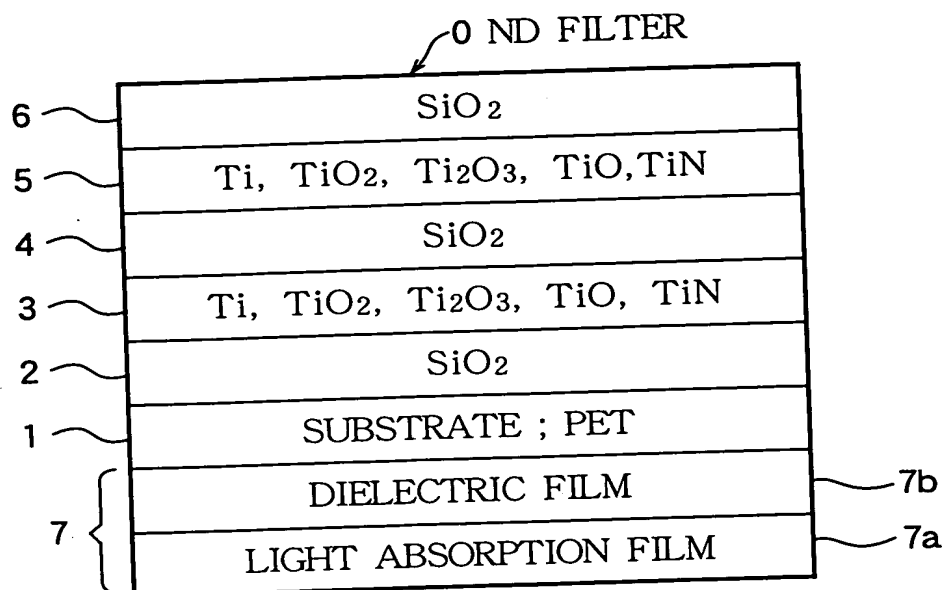


FIG. 11

